IDC Low Inductance Capacitors (RoHS)

IDC (InterDigitated Capacitors) 0306/0612/0508

GENERAL DESCRIPTION

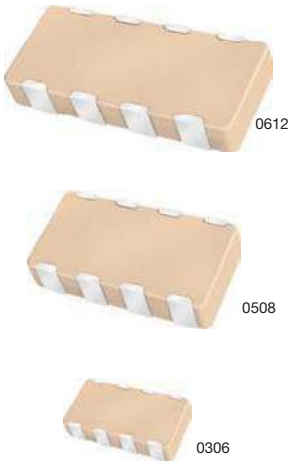
Inter-Digitated Capacitors (IDCs) are used for both semiconductor package and board level decoupling. The equivalent series inductance (ESL) of a single capacitor or an array of capacitors in parallel determines the response time of a Power Delivery Network (PDN). The lower the ESL of a PDN, the faster the response time. A designer can use many standard MLCCs in parallel to reduce ESL or a low ESL Inter-Digitated Capacitor (IDC) device. These IDC devices are available in versions with a maximum height of 0.95mm or 0.55mm.

IDCs are typically used on packages of semiconductor products with power levels of 15 watts or greater. Inter-Digitated Capacitors are used on CPU, GPU, ASIC, and ASSP devices produced on 0.13µ, 90nm, 65nm, and 45nm processes. IDC devices are used on both ceramic and organic package substrates. These low ESL surface mount capacitors can be placed on the bottom side or the top side of a package substrate. The low profile 0.55mm maximum height IDCs can easily be used on the bottom side of BGA packages or on the die side of packages under a heat spreader.

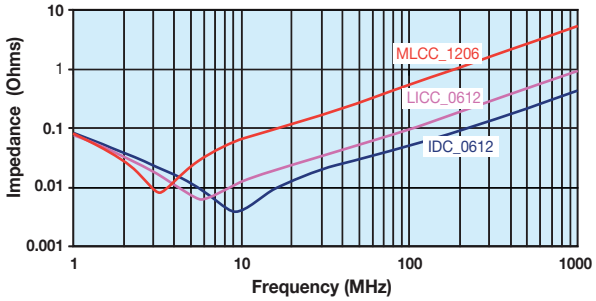
IDCs are used for board level decoupling of systems with speeds of 300MHz or greater. Low ESL IDCs free up valuable board space by reducing the number of capacitors required versus standard MLCCs. There are additional benefits to reducing the number of capacitors beyond saving board space including higher reliability from a reduction in the number of components and lower placement costs based on the need for fewer capacitors.

The Inter-Digitated Capacitor (IDC) technology was developed by KYOCERA AVX. This is the second family of Low Inductance MLCC products created by KYOCERA AVX. IDCs are a cost effective alternative to KYOCERA AVX's first generation low ESL family for high-reliability applications known as LICA (Low Inductance Chip Array).

KYOCERA AVX IDC products are available with a lead-free finish of plated Nickel/ Tin.



TYPICAL IMPEDANCE



HOW TO ORDER

W	3	L	1	6	D	225	M	A	T	3	A
Style	IDC Case Size 2 = 0508 3 = 0612 4 = 0306	Low Inductance	Number of Terminals 1 = 8 Terminals	Voltage 4 = 4V 6 = 6.3V Z = 10V Y = 16V 3 = 25V	Dielectric C = X7R D = X5R Z = X7S	Capacitance Code (In pF) 2 Sig. Digits + Number of Zeros	Capacitance Tolerance M = ±20%	Failure Rate A = N/A	Termination T =Plated Ni and Sn	Packaging Available 1=7" Reel 3=13" Reel	Thickness Max. Thickness mm (in) A=Standard S=0.55 (0.022)

NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers.

RoHS COMPLIANT

PERFORMANCE CHARACTERISTICS

Capacitance Tolerance	±20% Preferred
Operation Temperature Range	X7R = -55°C to +125°C X5R = -55°C to +85°C X7S = -55°C to +125°C
Temperature Coefficient	±15% (0VDC), ±22% (X7S)
Voltage Ratings	4, 6.3, 10, 16, 25 VDC
Dissipation Factor	≤ 6.3V = 6.5% max; 10V = 5.0% max; ≥ 16V = 3.5% max
Insulation Resistance (@+25°C, RVDC)	100,000MΩ min, or 1,000MΩ per µF min.,whichever is less

Dissipation Factor	No problems observed after 2.5 x RVDC for 5 seconds at 50mA max current
CTE (ppm/C)	12.0
Thermal Conductivity	4-5W/M K
Terminations Available	Plated Nickel and Solder

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SIZE		W4 = 0306		W2 = Thin 0508					W2 = 0508					W3= Thin 0612				W3 = 0612					W3 = THICK 0612			
Max. Thickness	mm (in.)	0.55 (0.022)		0.55. (0.022)					0.95 (0.037)					0.55 (0.022)				0.95 (0.037)					1.22 (0.048)			
WVDC		4	6.3	4	6.3	10	16	25	4	6.3	10	16	25	4	6.3	10	16	4	6.3	10	16	25	4	6.3	10	16
Cap (µF)	0.010																									
	0.022																									
	0.033																									
	0.047																									
	0.068																									
	0.10																									
	0.22																									
	0.33																									
	0.47																									
	0.68																									
	1.0																									
	1.5																									
	2.2																									
	3.3																									

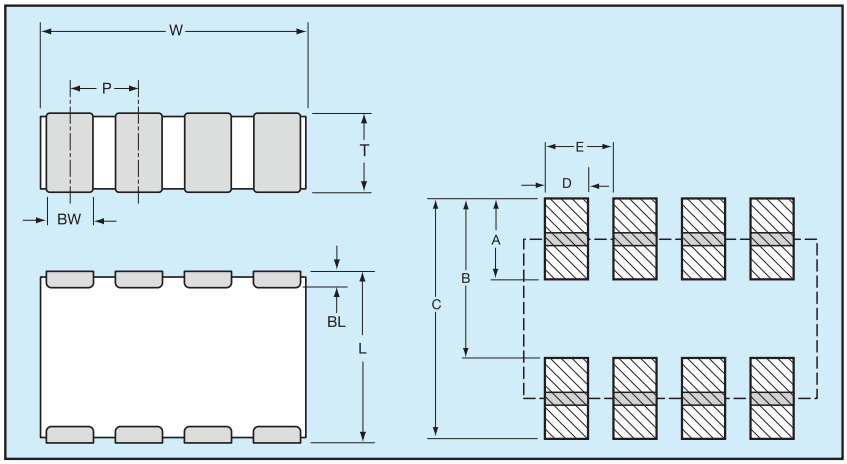
Consult factory for additional requirements

= X7R

= X5R

= X7S

PHYSICAL DIMENSIONS AND PAD LAYOUT



PHYSICAL CHIP DIMENSIONS

MILLIMETERS (INCHES)

SIZE	W	L	BW	BL	P
0306	1.60 ± 0.20 (0.063 ± 0.008)	0.82 ± 0.10 (0.032 ± 0.006	0.25 ± 0.10 (0.010 ± 0.004)	0.20 ± 0.10 (0.008± 0.004)	0.40 ± 0.05 (0.015 ± 0.002)
0508	2.03 ± 0.20 (0.080 ± 0.008)	1.27 ± 0.20 (0.050 ± 0.008)	0.30 ± 0.10 (0.012 ± 0.004)	0.25 ± 0.15 (0.010± 0.006)	0.50 ± 0.05 (0.020 ± 0.002)
0612	3.20 ± 0.20 (0.126 ± 0.008)	1.60 ± 0.20 (0.063 ± 0.008)	0.50 ± 0.10 (0.020 ± 0.004)	0.25 ± 0.15 (0.010 ± 0.006)	0.80 ± 0.10 (0.031 ± 0.004)

PAD LAYOUT DIMENSIONS

SIZE	A	B	C	D	E
0306	0.38 (0.015)	0.89 (0.035)	1.27 (0.050)	0.20 (0.008)	0.40 (0.015)
0508	0.64 (0.025)	1.27 (0.050)	1.91 (0.075)	0.28 (0.011)	0.50 (0.020)
0612	0.89 (0.035)	1.65 (0.065)	2.54 (0.010)	0.45 (0.018)	0.80 (0.031)